(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
6 May 2004 (06.05.2004)

PCT

(10) International Publication Number
WO 2004/037447 A1

(51) International Patent Classification[7]: B05D 5/12, B32B 9/00

(21) International Application Number: PCT/US2003/033353

(22) International Filing Date: 21 October 2003 (21.10.2003)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/419,873 21 October 2002 (21.10.2002) US

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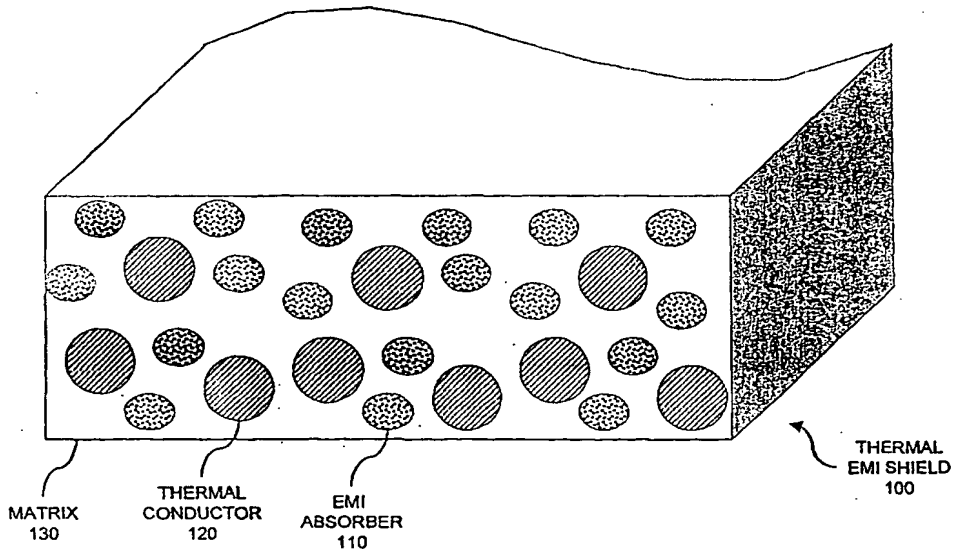
(81) Designated States *(national)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States *(regional)*: ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— *with international search report*
— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*

[Continued on next page]

(54) Title: THERMALLY CONDUCTIVE EMI SHIELD



(57) Abstract: Electromagnetic-energy absorbing materials are combined with thermally conductive materials, such as those used for thermal management in association with electronic equipment, thereby suppressing the transmission of electromagnetic interference (EMI) therethrough. Disclosed are materials and processes for combining EMI-absorbing materials with thermally conductive materials thereby improving EMI shielding effectiveness in an economically efficient manner. In one embodiment, a thermally conductive EMI absorber is prepared by combining an EMI-absorbing material (for example, ferrite particles) with a thermally conducting material (for example, ceramic particles), each suspended within an elastomeric matrix (for example, silicone). In application, a layer of thermally conductive EMI-absorbing material is applied between an electronic device or component, and a heat sink

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